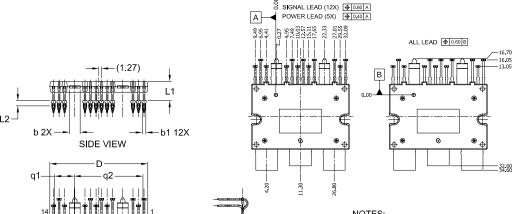


APM17-MFA, AUTOMOTIVE MODULE CASE MODBM

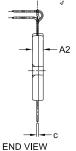
ISSUE A

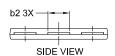
DATE 12 OCT 2022

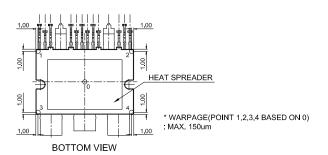




2X ØA MARK AREA TOP VIEW







NOTES:

- 1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS ARE EXCLUSIVE OF BURRS. MOLD FLASH AND TIE BAR EXTRUSIONS.

	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
A2	4.90	5.00	5.10	
b	4.80	4.90	5.00	
b1	1.61	1.66	1.71	
b2	9.90	10.00	10.10	
С	0.75	0.80	0.90	
D	44.90	45.00	45.10	
E1	29.90	30.00	30.10	
E2	11.20	11.30	11.40	
L1	8.49	8.79	9.09	
L2	2.31	2.41	2.51	
q1	8.90	9.00	9.10	
q2	31.50	31.60	31.70	
ΦA	3.65	3.75	3.85	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code ZZZ = Assembly Lot Code

= Assembly Site

Т = Test Site

= Year

WW = Work Week

NN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	PTION: APM17-MFA, AUTOMOTIVE MODULE		PAGE 1 OF 1

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